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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	40	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 6) V_{GS} = 10V	Steady State	T_C = +25°C T_C = +70°C	I_D	39 31	A
	Steady State	T_A = +25°C T_A = +70°C	I_D	11.9 9.5	A
Maximum Body Diode Forward Current (Note 6)			I_S	2	A
Pulsed Drain Current (10µs pulse, Duty cycle = 1%)			I_{DM}	80	A
Avalanche Current (Notes 7) L = 0.1mH			I_{AS}	27	A
Avalanche Energy (Notes 7) L = 0.1mH			E_{AS}	37	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)		P_D	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{\theta JA}$	78	°C/W
	t<10s		31	
Total Power Dissipation (Note 6)		P_D	2.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	51	°C/W
	t<10s		21	
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	4.7	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	40	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current T_J = +25°C	I_{DSS}	—	—	1	µA	V_{DS} = 32V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(th)}$	1.0	—	3.0	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS\ (ON)}$	—	8.7	11.5	mΩ	V_{GS} = 10V, I_D = 14A
			11.1	14.5		V_{GS} = 4.5V, I_D = 11A
Diode Forward Voltage	V_{SD}	—	0.72	—	V	V_{GS} = 0V, I_S = 14A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	1810	—	pF	V_{DS} = 20V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	135	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	112	—	pF	
Gate Resistance	R_g	—	1.7	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	17	—	nC	V_{DS} = 20V, , I_D = 14A
Total Gate Charge (V_{GS} = 10V)	Q_g	—	37	—	nC	
Gate-Source Charge	Q_{gs}	—	5.6	—	nC	
Gate-Drain Charge	Q_{gd}	—	7.1	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	5.1	—	ns	V_{GS} = 10V, V_{DS} = 20V, R_G = 6Ω, I_D = 14A
Turn-On Rise Time	t_r	—	13	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	36	—	ns	
Turn-Off Fall Time	t_f	—	13	—	ns	
Body Diode Reverse Recovery Time	t_{rr}	—	12.2	—	ns	I_S = 3A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{rr}	—	5.4	—	nC	I_S = 3A, dI/dt = 100A/µs

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = 25°C
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.

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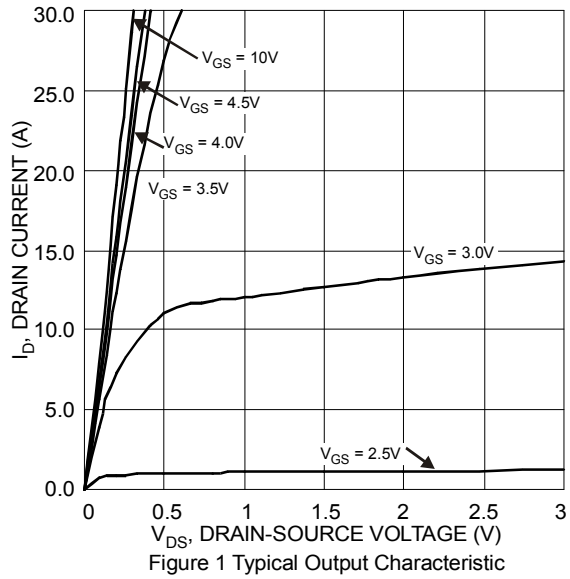

Figure 1 Typical Output Characteristic

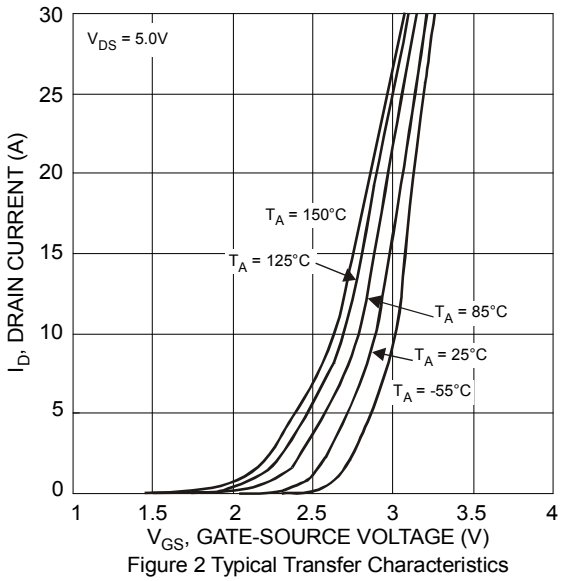

Figure 2 Typical Transfer Characteristics

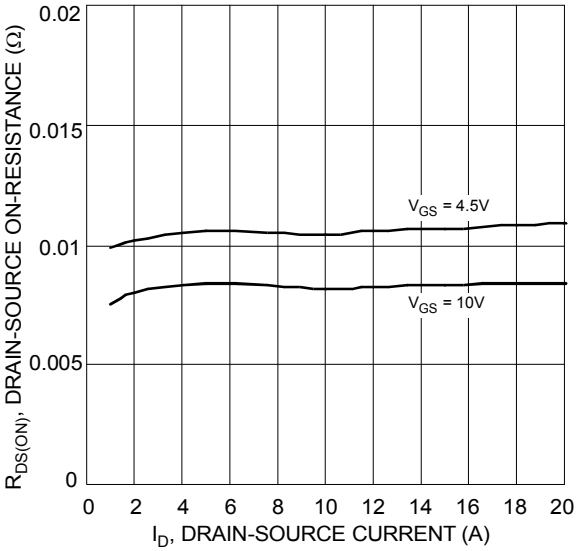

Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

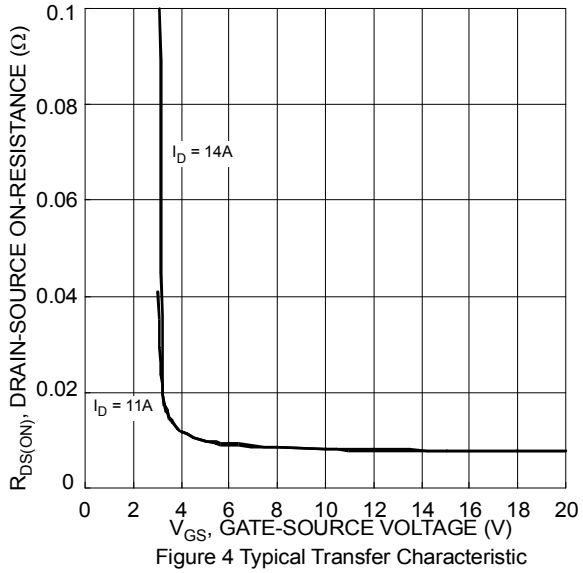

Figure 4 Typical Transfer Characteristic

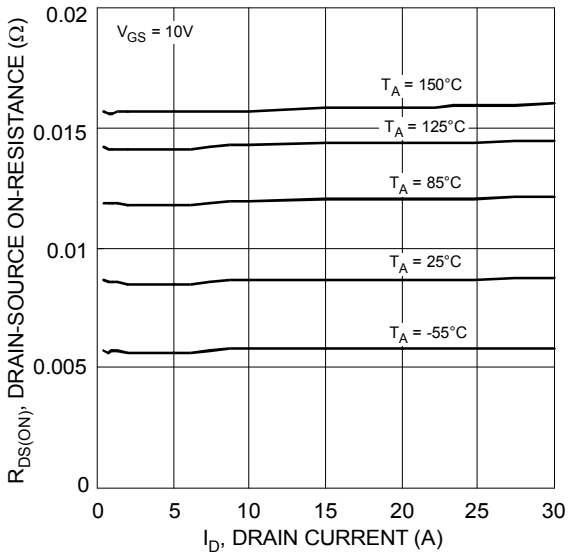

Figure 5 Typical On-Resistance vs. Drain Current and Temperature

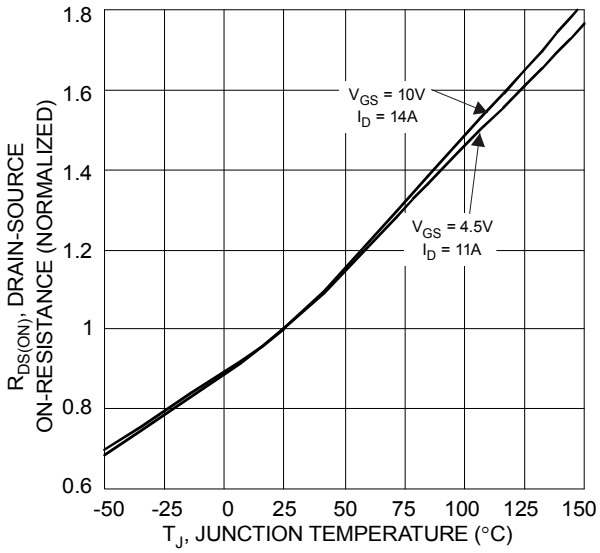

Figure 6 On-Resistance Variation with Temperature

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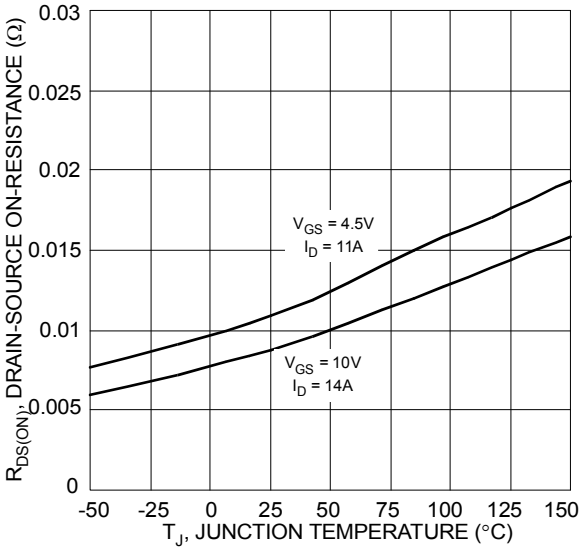

Figure 7 On-Resistance Variation with Temperature

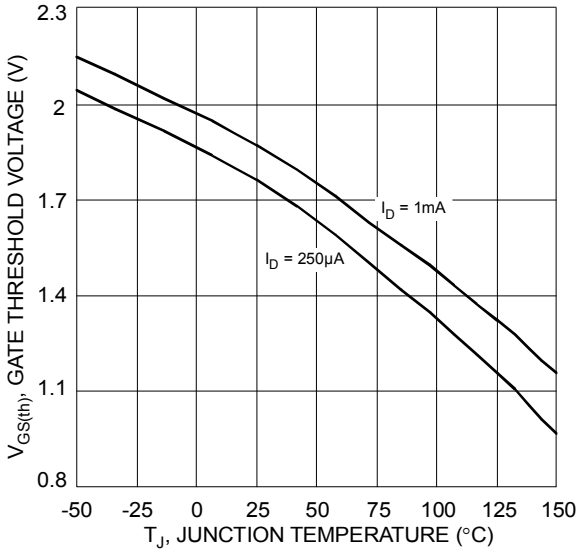

Figure 8 Gate Threshold Variation vs. Ambient Temperature

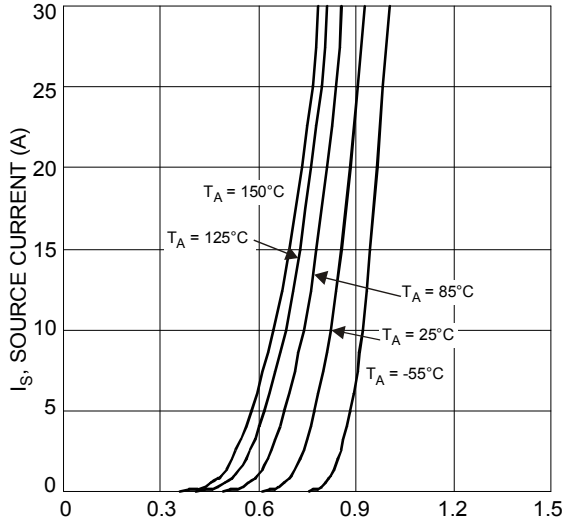

Figure 9 Diode Forward Voltage vs. Current

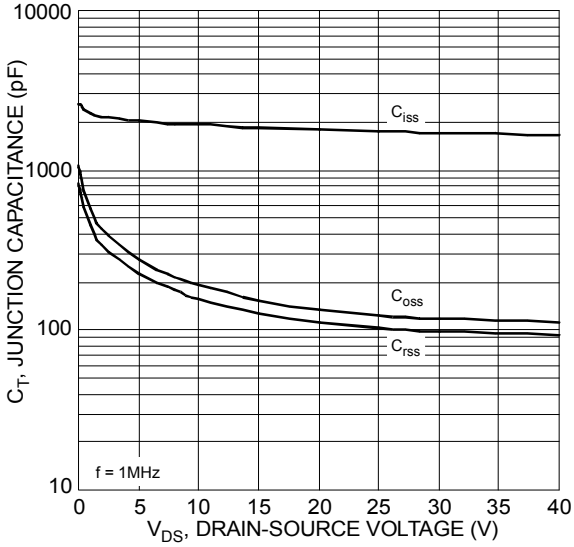

Figure 10 Typical Junction Capacitance

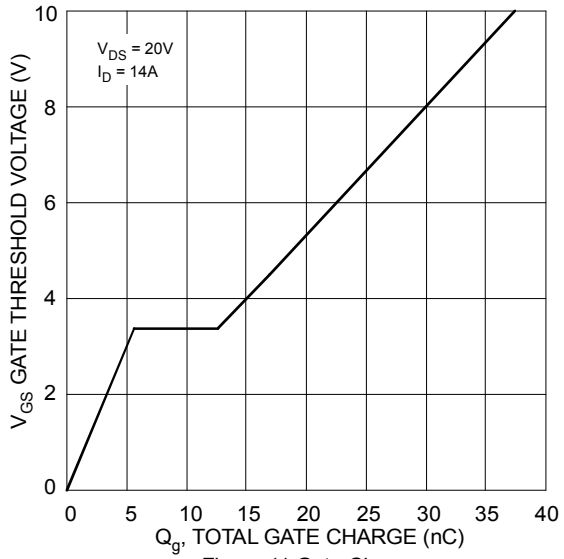

Figure 11 Gate Charge

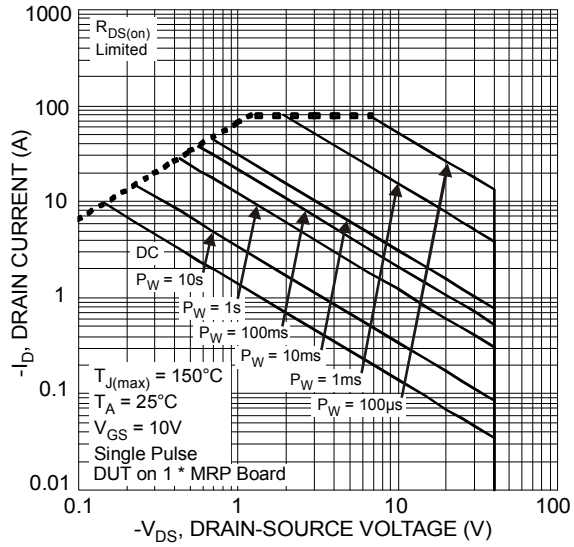

Figure 12 SOA, Safe Operation Area

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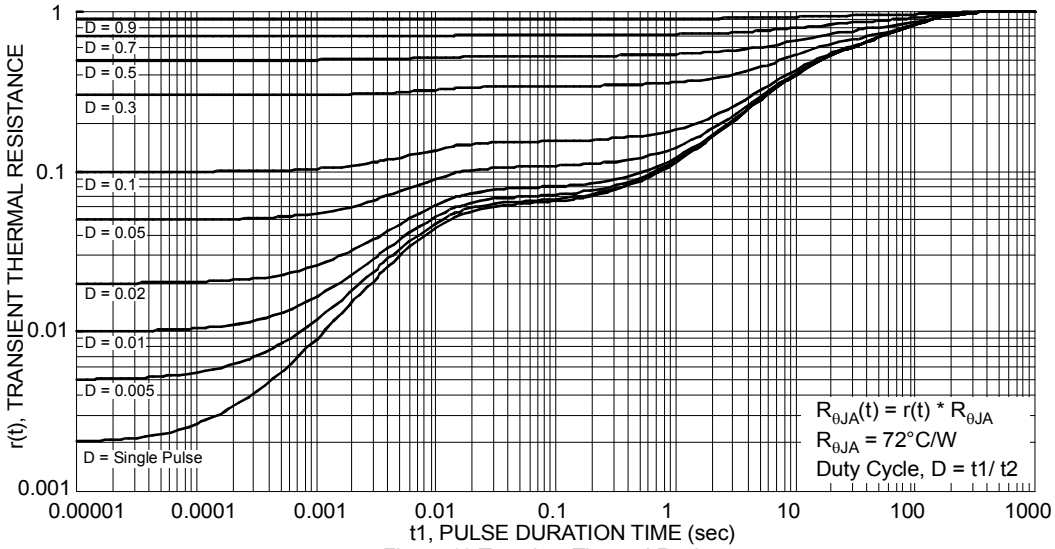
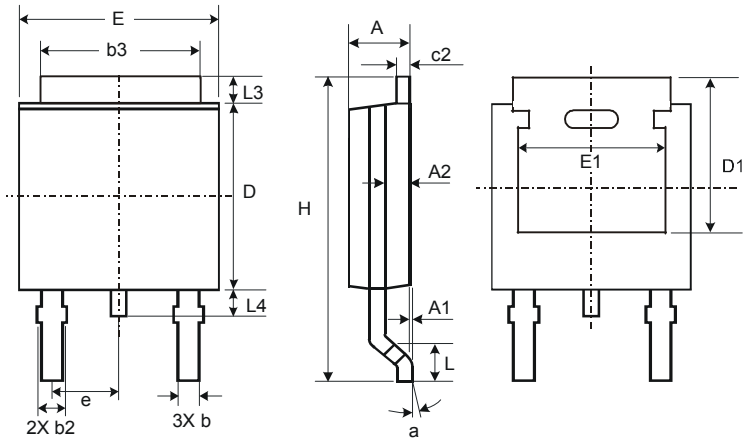


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

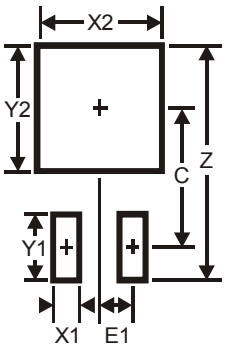
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TO252			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c2	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	–	–
e	–	–	2.286
E	6.45	6.70	6.58
E1	4.32	–	–
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	–
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
C	6.9
E1	2.3

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